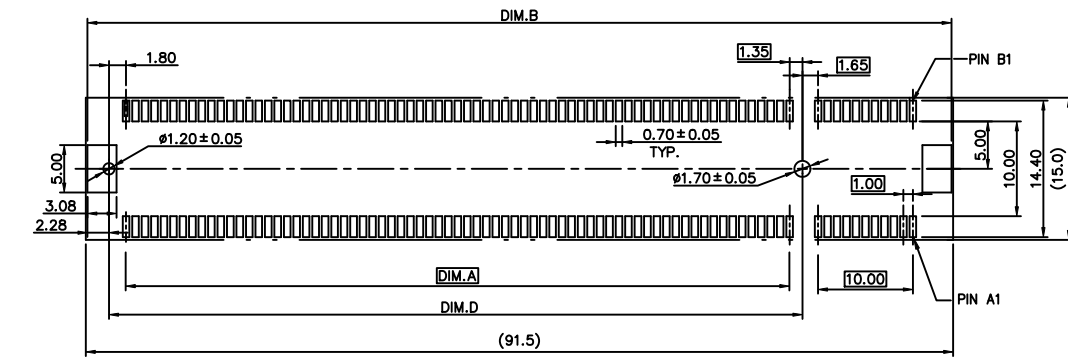
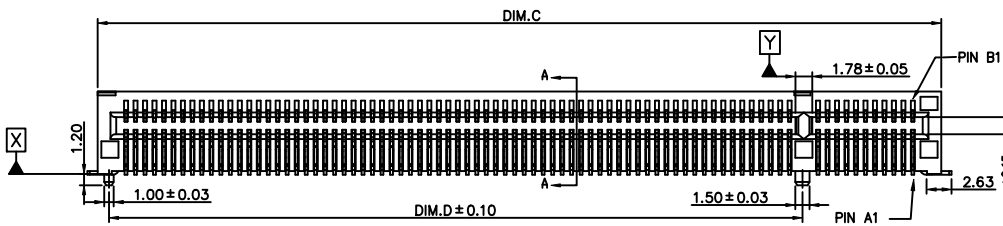
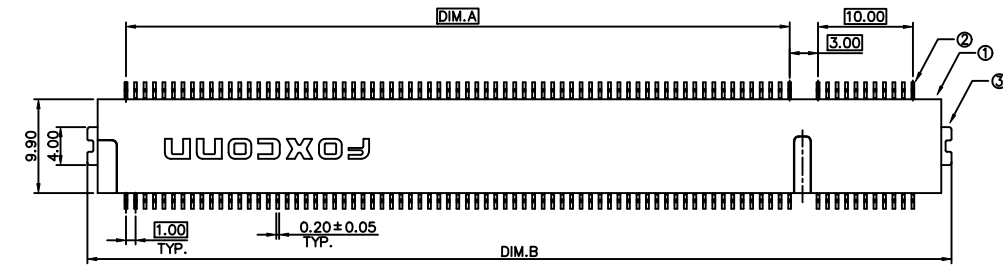


REV.	ECN NO.	APPD.
A	BC-15-0001368	Davy Bu
B	BC-15-0055133	Davy Bu

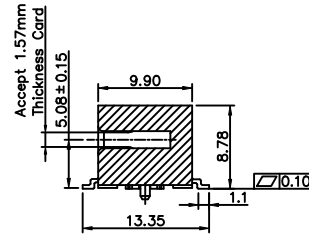


RECOMMENDED PCB LAYOUT

2EGL499*-B2D*-**	37.00	58.15	56.00	40.15	58.5
2EGL829*-B2D*-**	70.00	91.15	89.00	73.15	91.5
PART NO.	DIM.A	DIM.B	DIM.C	DIM.D	DIM.E

NOTE:

- ELECTRICAL CHARACTERISTICS:
  - INSULATION RESISTANCE: 1000 MEGAOHMS MIN.
  - DIELECTRIC WITHSTAND VOLTAGE: 500VAC RMS. MIN. AT SEA LEVEL.
  - SIGNAL CONTACT RESISTANCE: 30 MILLIOHMS MAX. INITIAL. 50 MILLIOHMS MAX. AFTER TEST.
- MECHANICAL CHARACTERISTICS:
  - DURABILITY: 50 CYCLES.
  - CONTACT RETENTION FORCE: 0.5Kgf MIN.
  - TAIL COPLANARITY TO BE 0.10mm MAX. PCB COPLANARITY TO BE 0.03mm MAX. ON CONNECTOR AREA.
- ENVIRONMENTAL CHARACTERISTICS:
  - OPERATION TEMPERATURE RANGE : -55°C TO +105°C.



SECTION A-A

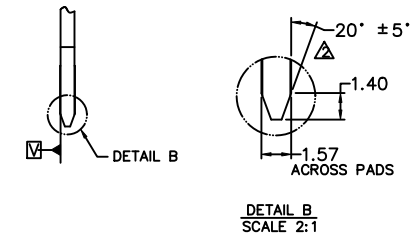
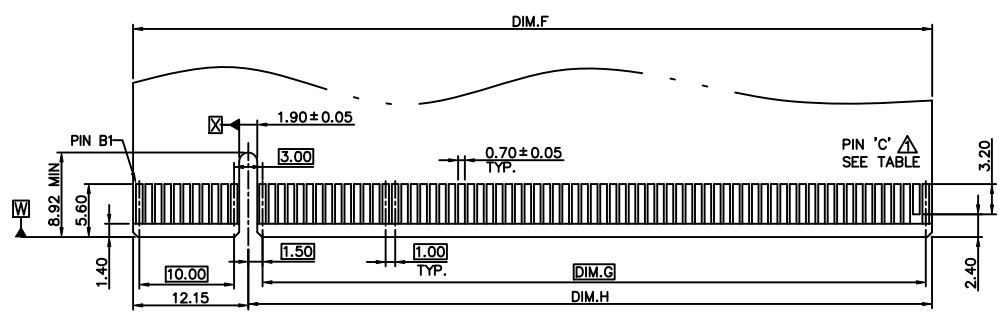
PROD. NO. 2EG L \*\* 9 \* - B2D \* - \*\*

SERIES PREFIX: PCI-E	GREEN CODE
TERMINATION TYPE: L: R/A GEN3.0	4H: LEAD FREE & HALOGEN FREE ROHS COMPLIANT
NO. OF POS.: 49: 98 POS. 82: 164 POS.	4F: LEAD FREE ROHS COMPLIANT
FOR SMT	0: NONE M: MATTE TIN EXTENSION CODE
	GOLD PLATING: 1: GOLD FLASH 3: 30u" GOLD 7: 15u" GOLD

3	PAD	2	COPPER ALLOY,PH/BR	NICKEL PLATING OVER ALL UNDERPLATED. TIN PLATING OVER NICKEL.
2	CONTACT	SEE P/N	COPPER ALLOY,PH/BR	NICKEL PLATING OVER ALL UNDERPLATED. TIN PLATING OVER NICKEL AT TAIL. GOLD PLATING ON CONTACT AREA.
1	HOUSING	1	THERMOPLASTIC,LCP	MOLDED BLACK
ITEM	DESCRIPTION	Q'TY	MATERIAL	TREATMENT
X.±	X.±	UNITS	mm	NAME(INTENDED USE)
.X±	.X±	MAT'L	N/A	R/A Gen3.0 SMT PCI-E
.XX±	.XX±	FINISH	N/A	PART NO.(INTENDED USE)
.XXX±	.XXX±			2EGL****-B2D*-**
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.				CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
APPD: Davy Bu 11/10'15				TITLE: CUSTOMER DRAWING
CHKD: Johnny Tang 11/10'15				DWG NO.: 303-0000-3155
DR: Qin Teng 11/10'15				SCALE SHEET REV.
				1:1 1/2 B

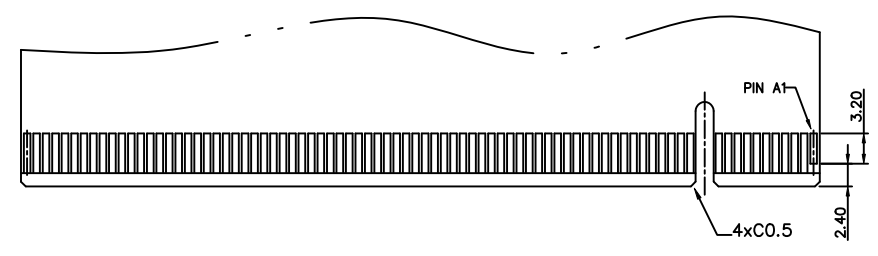
REV.	ECN NO.	APPD.

SEE SHEET 1



— /O PANEL DIRECTION

PRIMARY (COMPONENT) SIDE



SECONDARY (SOLDER) SIDE

NOTES:

- △ NO TIE PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND 'C'.
- △ CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

2EGL499*-B2D*-**	98/8X	B48
2EGL829*-B2D*-**	164/16X	BB1
PART NUMBER	NO POS /WAY	c △

2EGL499*-B2D*-**	51.30	37.00	39.15
2EGL829*-B2D*-**	84.30	70.00	72.15
PART NO.	DIM.F	DIM.G	DIM.H

X.±	X'.±	z'	UNITS	mm	NAME (INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED		
.X±	.X'±	1'	MAT'L	N/A	R/A Gen3.0 SMT PCI-E			
.XX±	.XX±				PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL		
.XXX±	.XXX±		FINISH	N/A	2EGL****-B2D*-**	TITLE: CUSTOMER DRAWING		
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					Q'TY	N/A	CHKD:	303-0000-3155
							DR:	SCALE SHEET REV.
					Davy Bu 11/10'15	1:1 2/2 B		
					Johnny Tang 11/10'15			
					Qin Teng 11/10'15			